ASSOCIATION CONNECTING LECTRONICS INDUSTRIES INDUSTRIES	ckburn, Illinois, A	All rights reserved un entions.	der both This docur level parts	nent is a declara the declaration	tion of the substa encompasses all	nces within the manufactu lower level materials for w	rer listed item. Note: i	f the item is an a r has engineering	ssembly with lower responsibility.		
IPC Web Site for Information	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Inform				ion			
Supplier Information											
mpany name* Company unique ID		ique ID		Unique ID Authority			Response Date*				
semi							2023-06-08				
tact Name Title - Contact				Phone - Contact*			Email - Contact*				
duct-Env-Stewards Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*	orized Representative* Title - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr	tem Number	Mfr Item Name		Effective Dat	e Version	Manufacturing Site	Weight*	UOM	Unit Type		
NCP	CP4305DDR2G Secondary Side S Driver for High E		nchronous Rectification ficiency SMPS Topologie	s 2023-06-08	2023-06-08 TH2		71.91	mg	Each		
Manufacturing Proccess Information											
Terminal Plating / Grid Array Material	Terminal Base Alloy J		STD-020 MSL Rating	Peak Process Body Temperat		erature Max Time at Peak	Temperature Numb	per of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy 3			260	С	30	seconds 3					
Comments											
ATTENTION: MSL 3 Rated item requires Bake ar	d Dry Pack (afte	r electrical test)									
For more information regarding material composit	on please refer t	o page 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg		Epoxy resin	proprietary data		0.312	mg
			Supplier	Silver (Ag)	7440-22-4		0.84	mg
			Supplier	Acrylic resins	Proprietary Data		0.408	mg
			Supplier	Aluminum (Al)	7429-90-5		0.84	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.1128	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0715	mg
			Supplier	Iron (Fe)	7439-89-6		0.9741	mg
			Supplier	Copper (Cu)	7440-50-8		36.399	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0527	mg
Mold Compound-Black	28.58	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		1.2861	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.2936	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.8574	mg
lating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond	0.1	mg	Supplier	Palladium (Pd)	7440-05-3		0.0021	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0976	mg